



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Biswajit Sur et al.

Title: ELECTRONIC ASSEMBLY COMPRISING SOLDERABLE THERMAL INTERFACE AND METHODS OF MANUFACTURE

Docket No.: 884.319US2

Filed: February 9, 2004

Examiner: Andy Huynh

Customer No.: 21186

Serial No.: 10/775,890

Due Date: April 17, 2006

Group Art Unit: 2818

Confirmation No.: 1421

Commissioner for Patents

Attn: MAIL STOP ISSUE FEE

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Notice of Allowance Date:

January 17, 2006

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SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number: 21186

By Ann M. McCrackin

Ann M. McCrackin

Reg. No. 42,858

AMM1:CMG:clh

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Attn – MAIL STOP ISSUE FEE, P.O. Box 1450, Alexandria, VA 22313-1450, on this 17 day of April, 2006.

Chris Hammond
Name

Chris Hammond
Signature

S/N 10/775,890

APR 20 2006

PATENT

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Serial No.: 10/775,890 Group Art Unit: 2818
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Title: ELECTRONIC ASSEMBLY COMPRISING SOLDERABLE
THERMAL INTERFACE AND METHODS OF MANUFACTURE
Assignee: Intel Corporation Customer No. 21186

COMMUNICATION CONCERNING RELATED APPLICATION(S)

MS Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date/Issue Date</u>	<u>Attorney Docket</u>	<u>Title</u>
09/652430	August 31, 2000	884.319US1	ELECTRONIC ASSEMBLY
6724078	April 20, 2004		COMPRISING SOLDERABLE
			THERMAL INTERFACE (As Amended)

Continuations and divisionals may be later filed on the cases listed above, or cited to the Examiner in any previous Communication Concerning Related Applications. Applicants request that the Examiner review all continuations and divisionals of the above-listed or previously-cited patent applications before allowing the claims of the present patent application.

Respectfully submitted,
BISWAJIT SUR ET AL.
By their Representatives,
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Date April 17, 2006 By Ann M. McCrackin
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Chris Hammond
Name

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